Unit: mm

TOSHIBA Schottky Barrier Rectifier Schottky Barrier Type

CUS05

Switching Mode Power Supply Applications
Portable Equipment Battery Application

- Forward voltage: $V_{FM} = 0.37 \text{ V (max)} @I_F = 0.7 \text{ A}$
- Average forward current: IF (AV) = 1.0 A
- Repetitive peak reverse voltage: V_{RRM} = 20 V
- Suitable for high-density board assembly due to the use of a small Surface-mount package, US-FLATTM

Absolute Maximum Ratings (Ta = 25°C)

Characteristics	Symbol	Rating	Unit
Repetitive peak reverse voltage	V_{RRM}	20	V
Average forward current	I _{F (AV)}	1.0 (Note 1)	A
Peak one cycle surge forward current	\ 	20 (50 Hz)	A
(Non-repetitive)	IFSM	20 (50 HZ)	A
Junction temperature	Tj	+40 to 125	°C
Storage temperature range	Tstg	-40 to 150	O°C

Note: Using continuously under heavy loads (e.g. the application of high temperature/current/voltage and the significant change in temperature, etc.) may cause this product to decrease in the

temperature, etc.) may cause this product to decrease in the reliability significantly even if the operating conditions (i.e. operating temperature/current/voltage, etc.) are

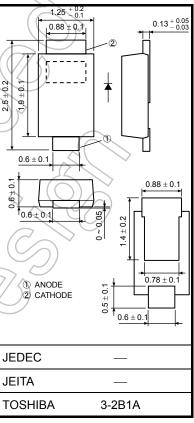
Please design the appropriate reliability upon reviewing the Toshiba Semiconductor Reliability Handbook ("Handling Precautions"/"Derating Concept and Methods") and individual reliability data (i.e. reliability test report and estimated failure rate, etc).

Note 1: Ta = 66°C: Device mounted on a ceramic board

within the absolute maximum ratings.

(board size: 50 mm × 50 mm, Soldering land: 2 mm × 2 mm)

Rectangular waveform ($\alpha = 180^{\circ}$), $V_R = 10 \text{ V}$



Weight: 0.004 g (typ.)



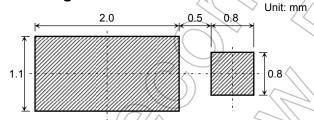
Electrical Characteristics (Ta = 25°C)

Characteristics	Symbol	Test Condition	Min	Тур.	Max	Unit	
Peak forward voltage	V _{FM (1)}	I _{FM} = 0.1 A	_	0.25	_		
	V _{FM (2)}	I _{FM} = 0.7 A	_	0.33	0.37	V	
	V _{FM (3)}	I _{FM} = 1.0 A	_	0.39	_		
Repetitive peak reverse current	I _{RRM (1)}	V _{RRM} = 5 V		50	_	μΑ	
Repetitive peak reverse current	I _{RRM (2)}	V _{RRM} = 20 V	(\leftarrow)	0.2	1.0	mA	
Junction capacitance	Cj	V _R = 10 V, f = 1.0 MHz		40	_	pF	
Thermal resistance (junction to ambient)	Bo a	Device mounted on a ceramic board (board size: 50 mm × 50 mm) (soldering land: 2 mm × 2 mm) (board thickness: 0.64 mm)	<u>(</u>)	_	75	- °C/W	
	™th (j-a)	Device mounted on a glass-epoxy board (board size: 50 mm × 50 mm) (soldering land: 6 mm × 6 mm) (board thickness: 1.6 mm)	_		150		
Thermal resistance (junction to lead)	R _{th (j-l)}	Junction to lead of cathode side	-6	7-/	> 30	°C/W	

Marking

Abbreviation Code	Part No.
5	CUS05

Standard Soldering Pad



Handling Precaution

Schottky barrier diodes have reverse current characteristic compared to the other diodes.

There is a possibility SBD may cause thermal runaway when it is used under high temperature or high voltage. This device is VF-IRRM trade-off type, lower VF higher IRRM; therefore, thermal runaway might occur when voltage is applied. Please take forward and reverse loss into consideration during design.

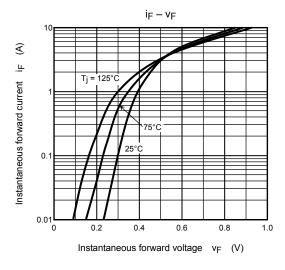
The absolute maximum ratings of a semiconductor device are a set of ratings that must not be exceeded, even for a moment. Do not exceed any of these ratings.

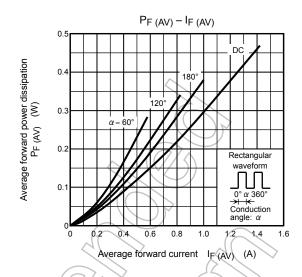
The following are the general derating methods that we recommend for designing a circuit using this device.

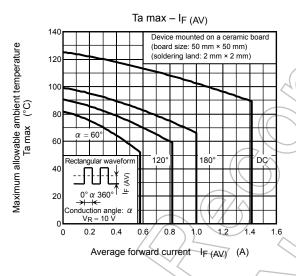
- VRRM: Use this rating with reference to the above. VRRM has a temperature coefficient of 0.1%/°C. Take this temperature coefficient into account designing a device at low temperature.
- IF(AV): We recommend that the worst case current be no greater than 80% of the absolute maximum rating of IF(AV) and T_j be below 100°C. When using this device, take the margin into consideration by using an allowable Tamax-IF(AV) curve.
- IFSM: This rating specifies the non-repetitive peak current. This is only applied for an abnormal operation, which seldom occurs during the lifespan of the device.
- T_j : Derate this rating when using a device in order to ensure high reliability. We recommend that the device be used at T_j of below 100°C.

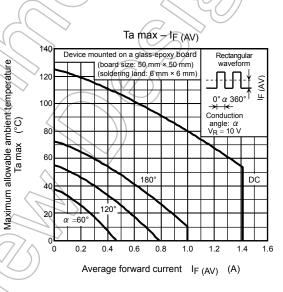
Thermal resistance between junction and ambient fluctuates depending on the device's mounting condition. When using a device, please design a circuit board and a soldering land size to match the appropriate thermal resistance value

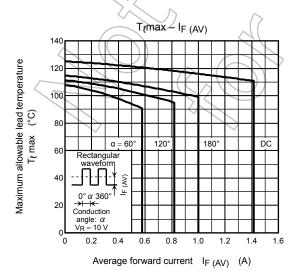
Refer to the Rectifiers databook for further information.

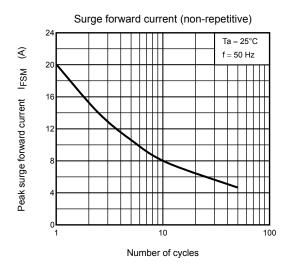




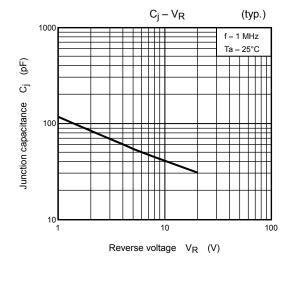


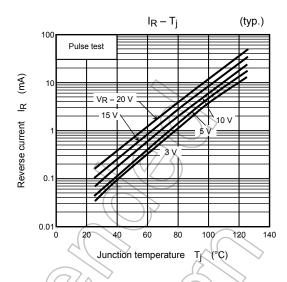


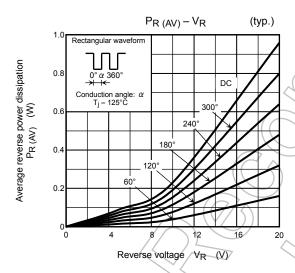


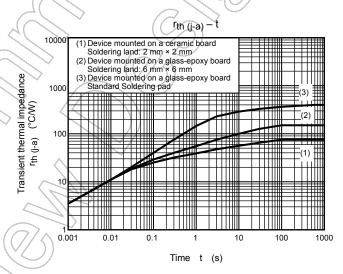


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